

# NTP75N03-06, NTB75N03-06

## Power MOSFET 75 Amps, 30 Volts

### N-Channel TO-220 and D<sup>2</sup>PAK

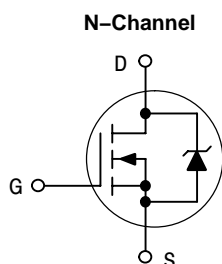
This 20 V<sub>GS</sub> gate drive vertical Power MOSFET is a general purpose part that provides the “best of design” available today in a low cost power package. This power MOSFET is designed to withstand high energy in the avalanche and commutation modes. The Drain-to-Source Diode has a fast response with soft recovery.

#### Features

- Ultra-Low R<sub>DS(on)</sub>, Single Base, Advanced Technology
- SPICE Parameters Available
- Diode is Characterized for Use in Bridge Circuits
- I<sub>DSS</sub> and V<sub>DS(on)</sub> Specified at Elevated Temperatures
- High Avalanche Energy Capability
- ESD JEDAC Rated HBM Class 1, MM Class B, CDM Class 0
- Pb-Free Packages are Available

#### Typical Applications

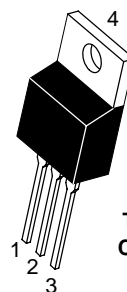
- Power Supplies
- Inductive Loads
- PWM Motor Controls
- Replaces MTP1306 and MTB1306



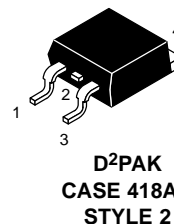
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V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> MAX
30 V	5.3 mΩ @ 10 V	75 A

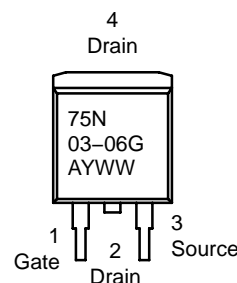
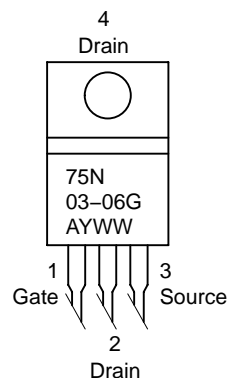


**TO-220AB  
CASE 221A  
STYLE 5**



**D<sup>2</sup>PAK  
CASE 418AA  
STYLE 2**

#### MARKING DIAGRAMS & PIN ASSIGNMENTS



N75N03-06 = Device Code  
 A = Assembly Location  
 Y = Year  
 WW = Work Week  
 G = Pb-Free Package

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

# NTP75N03-06, NTB75N03-06

## MAXIMUM RATINGS ( $T_J = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	$V_{DS}$	30	Vdc
Drain-to-Gate Voltage ( $R_{GS} = 10\text{ M}\Omega$ )	$V_{DGB}$	30	Vdc
Gate-to-Source Voltage – Continuous	$V_{GS}$	$\pm 20$	Vdc
Non-repetitive ( $t_p \leq 10\text{ ms}$ )	$V_{GS}$	$\pm 24$	Vdc
Drain Current <ul style="list-style-type: none"> <li>– Continuous @ <math>T_C = 25^\circ\text{C}</math></li> <li>– Continuous @ <math>T_C = 100^\circ\text{C}</math></li> <li>– Single Pulse (<math>t_p \leq 10\text{ }\mu\text{s}</math>)</li> </ul>	$I_D$ $I_D$ $I_{DM}$	75 59 225	Adc  Apk
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	125 1.0	W W/ $^\circ\text{C}$
Total Power Dissipation @ $T_A = 25^\circ\text{C}$ (Note 1)		2.5	W
Operating and Storage Temperature Range	$T_J$ and $T_{stg}$	$-55$ to $150$	$^\circ\text{C}$
Single Pulse Drain-to-Source Avalanche Energy – Starting $T_J = 25^\circ\text{C}$ ( $V_{DD} = 38\text{ Vdc}$ , $V_{GS} = 10\text{ Vdc}$ , $L = 1\text{ mH}$ , $I_L(pk) = 55\text{ A}$ , $V_{DS} = 40\text{ Vdc}$ )	$E_{AS}$	1500	mJ
Thermal Resistance <ul style="list-style-type: none"> <li>– Junction-to-Case</li> <li>– Junction-to-Ambient</li> <li>– Junction-to-Ambient (Note 1)</li> </ul>	$R_{\theta JC}$ $R_{\theta JA}$ $R_{\theta JA}$	1.0 62.5 50	$^\circ\text{C/W}$
Maximum Lead Temperature for Soldering Purposes, 1/8 in from case for 10 seconds	$T_L$	260	$^\circ\text{C}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. When surface mounted to an FR4 board using the minimum recommended pad size.

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
NTP75N03-06	TO-220	50 Units / Rail
NTP75N03-06G	TO-220 (Pb-Free)	50 Units / Rail
NTB75N03-06	D <sup>2</sup> PAK	50 Units / Rail
NTB75N03-06G	D <sup>2</sup> PAK (Pb-Free)	50 Units / Rail
NTB75N03-06T4	D <sup>2</sup> PAK	800 Units / Tape & Reel
NTB75N03-06T4G	D <sup>2</sup> PAK (Pb-Free)	800 Units / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# NTP75N03-06, NTB75N03-06

## ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Drain-Source Breakdown Voltage (Note 2) (V <sub>GS</sub> = 0 Vdc, I <sub>D</sub> = 250 μAdc) Temperature Coefficient (Negative)	V <sub>(BR)DSS</sub>	30	– –57	– –	Vdc mV/°C
Zero Gate Voltage Drain Current (V <sub>DS</sub> = 30 Vdc, V <sub>GS</sub> = 0 Vdc) (V <sub>DS</sub> = 30 Vdc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 150°C)	I <sub>DSS</sub>	– –	– –	1.0 10	μAdc
Gate-Body Leakage Current (V <sub>GS</sub> = ±20 Vdc, V <sub>DS</sub> = 0 Vdc)	I <sub>GSS</sub>	–	–	±100	nAdc

### ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage (Note 2) (V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μAdc) Threshold Temperature Coefficient (Negative)	V <sub>GS(th)</sub>	1.0 –	1.6 –6	2.0 –	Vdc mV/°C
Static Drain-to-Source On-Resistance (Note 2) (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 37.5 Adc)	R <sub>DS(on)</sub>	–	5.3	6.5	mΩ
Static Drain-to-Source On Resistance (Note 2) (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 75 Adc) (V <sub>GS</sub> = 10 Vdc, I <sub>D</sub> = 37.5 Adc, T <sub>J</sub> = 125°C)	V <sub>DS(on)</sub>	– –	0.53 0.35	0.68 0.50	Vdc
Forward Transconductance (Notes 2 & 4) (V <sub>DS</sub> = 3 Vdc, I <sub>D</sub> = 20 Adc)	g <sub>FS</sub>	–	58	–	Mhos

### DYNAMIC CHARACTERISTICS (Note 4)

Input Capacitance	(V <sub>DS</sub> = 25 Vdc, V <sub>GS</sub> = 0, f = 1.0 MHz)	C <sub>iss</sub>	–	4398	5635	pF
Output Capacitance		C <sub>oss</sub>	–	1160	1894	
Transfer Capacitance		C <sub>rss</sub>	–	317	430	

### SWITCHING CHARACTERISTICS (Notes 3 and 4)

Turn-On Delay Time	(V <sub>GS</sub> = 5.0 Vdc, V <sub>DD</sub> = 20 Vdc, I <sub>D</sub> = 75 Adc, R <sub>G</sub> = 4.7 Ω) (Note 2)	t <sub>d(on)</sub>	–	16	30	ns
Rise Time		t <sub>r</sub>	–	130	200	
Turn-Off Delay Time		t <sub>d(off)</sub>	–	65	110	
Fall Time		t <sub>f</sub>	–	105	175	
Gate Charge	(V <sub>GS</sub> = 5.0 Vdc, I <sub>D</sub> = 75 Adc, V <sub>DS</sub> = 24 Vdc) (Note 2)	Q <sub>T</sub>	–	57	75	nC
		Q <sub>1</sub>	–	11	15	
		Q <sub>2</sub>	–	34	50	

### SOURCE-DRAIN DIODE CHARACTERISTICS

Forward On-Voltage	(I <sub>S</sub> = 75 Adc, V <sub>GS</sub> = 0 Vdc) (I <sub>S</sub> = 75 Adc, V <sub>GS</sub> = 0 Vdc, T <sub>J</sub> = 125°C) (Note 2)	V <sub>SD</sub>	– –	1.19 1.09	1.25 –	Vdc
Reverse Recovery Time (Note 4)	(I <sub>S</sub> = 75 Adc, V <sub>GS</sub> = 0 Vdc dI <sub>S</sub> /dt = 100 A/μs) (Note 2)	t <sub>rr</sub>	–	37	–	ns
		t <sub>a</sub>	–	20	–	
Reverse Recovery Stored Charge (Note 4)		t <sub>b</sub>	–	17	–	μC
		Q <sub>RR</sub>	–	0.023	–	

- Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
- Switching characteristics are independent of operating junction temperatures.
- From characterization test data.

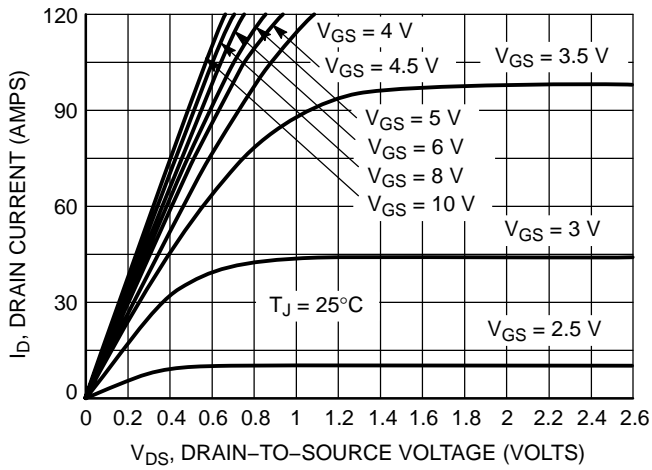


Figure 1. On-Region Characteristics

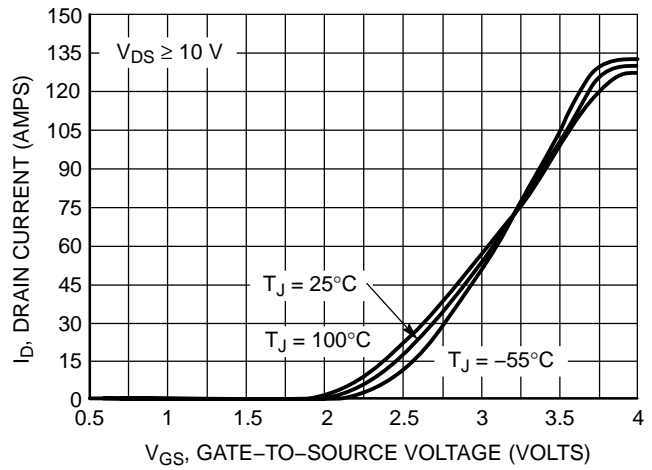


Figure 2. Transfer Characteristics

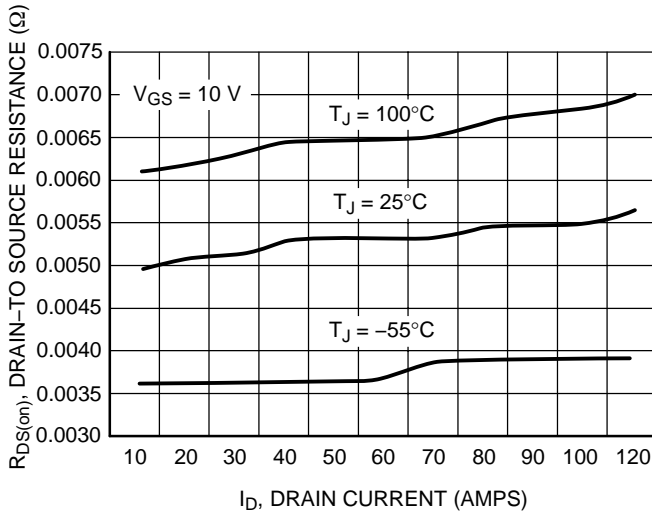


Figure 3. On-Resistance vs. Drain Current and Temperature

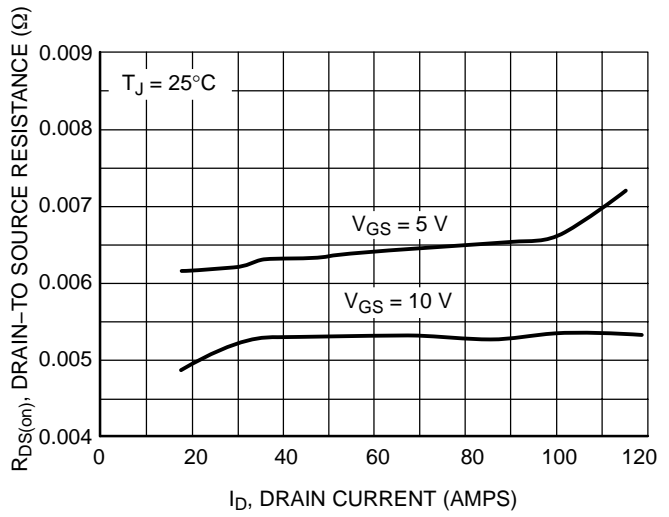


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

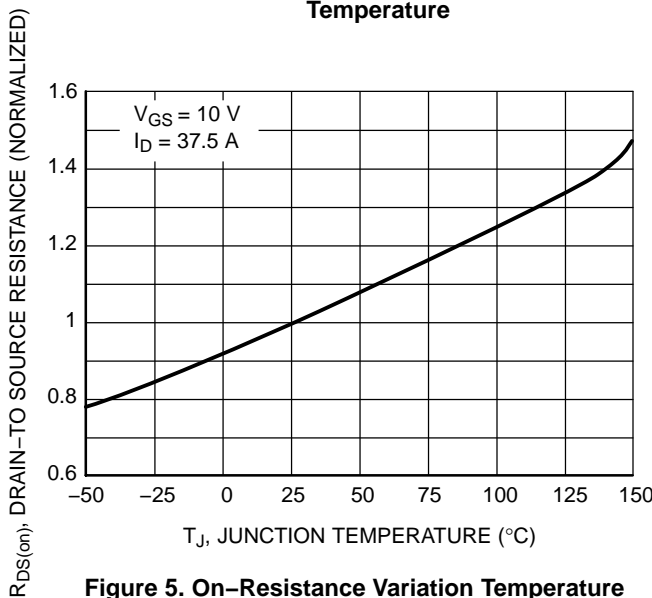


Figure 5. On-Resistance Variation Temperature

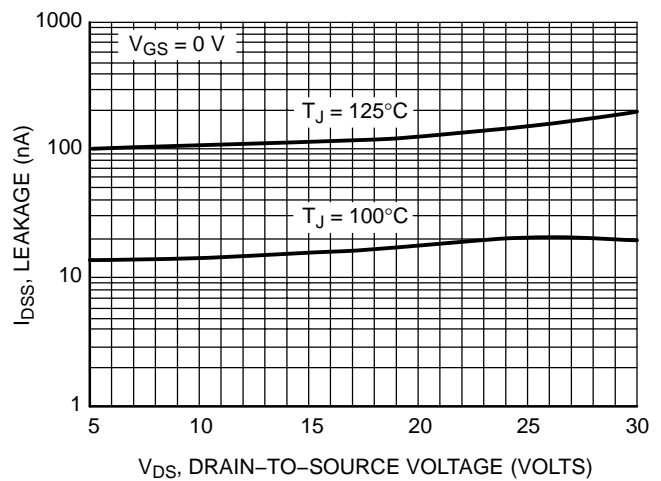


Figure 6. Drain-to-Source Leakage Current vs. Voltage

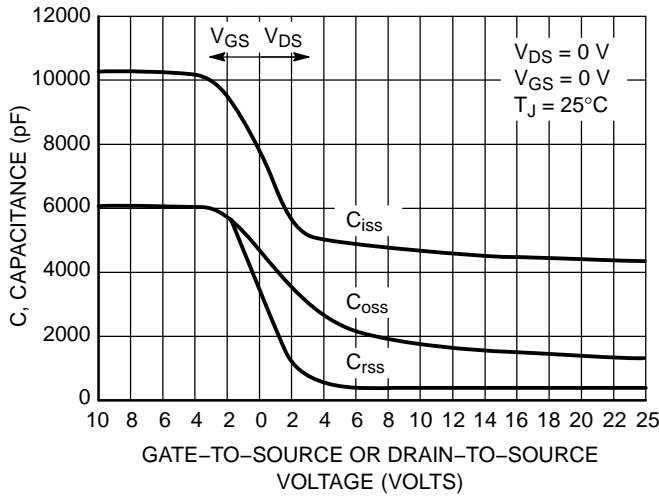


Figure 7. Capacitance Variation

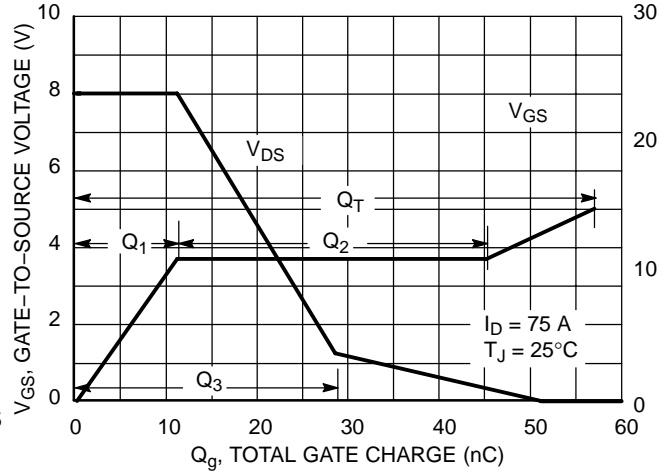


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

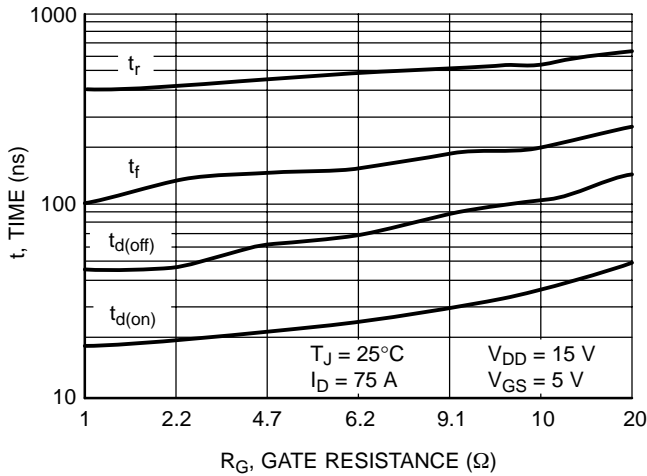


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

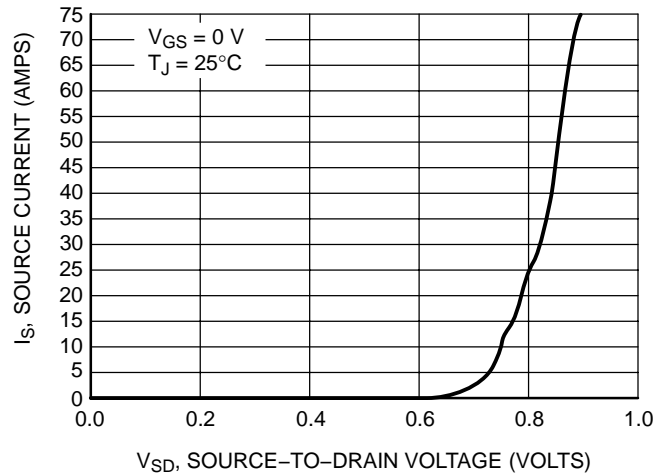


Figure 10. Diode Forward Voltage vs. Current

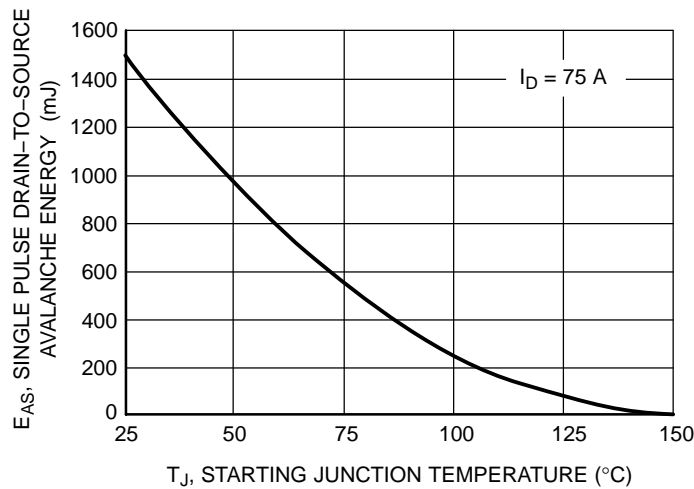
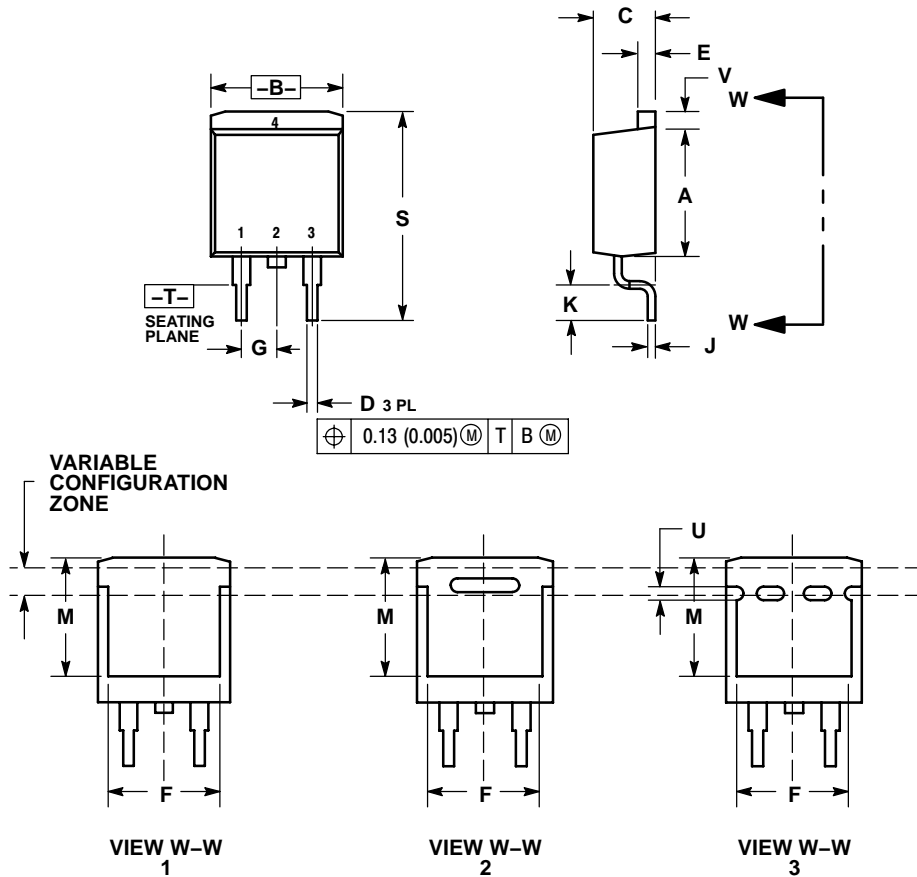


Figure 11. Maximum Avalanche Energy vs. Starting Junction Temperature

PACKAGE DIMENSIONS

D<sup>2</sup>PAK  
CASE 418AA-01  
ISSUE O

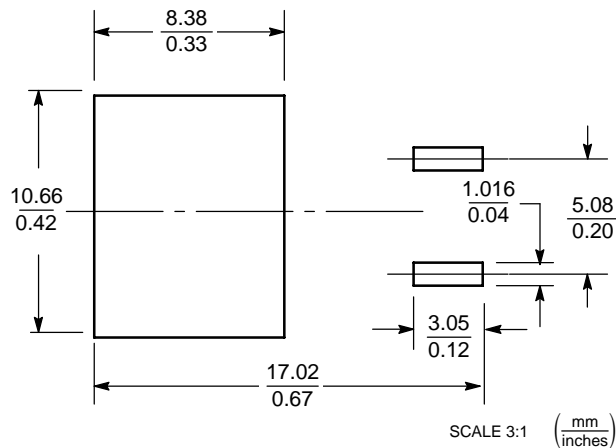


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.036	0.51	0.92
E	0.045	0.055	1.14	1.40
F	0.310	---	7.87	---
G	0.100 BSC	---	2.54 BSC	---
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
M	0.280	---	7.11	---
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

- STYLE 2:
1. GATE
  2. DRAIN
  3. SOURCE
  4. DRAIN

SOLDERING FOOTPRINT\*

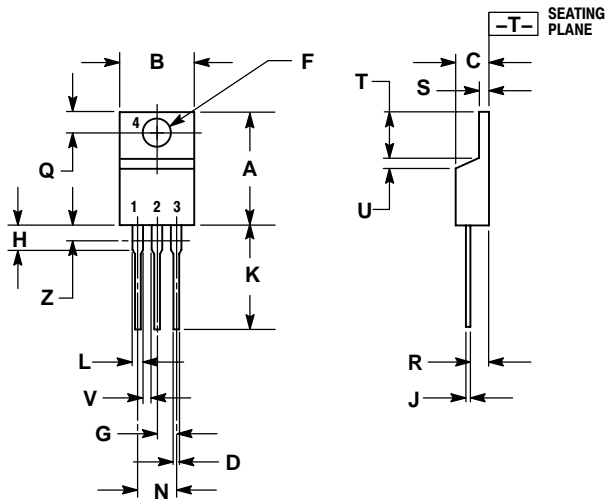


\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

# NTP75N03-06, NTB75N03-06

## PACKAGE DIMENSIONS

### TO-220 THREE-LEAD TO-220AB CASE 221A-09 ISSUE AA




#### NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.405	9.66	10.28
C	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
H	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

#### STYLE 5:

1. GATE
2. DRAIN
3. SOURCE
4. DRAIN

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